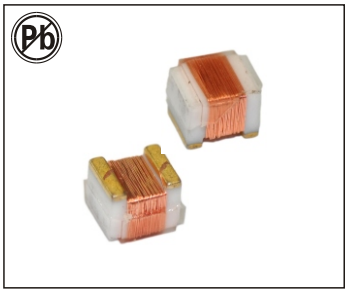
SURFACE-MOUNT WIRE WOUND CERAMIC CHIP INDUCTORS

AISC0402 SERIES



FEATURES:

- Multilayer monolithic construction yields high reliability
- High self-resonant frequency
- Excellentsolderability and heat resistance for either flow or reflow soldering

COMMON APPLICATIONS:

- High frequency circuits of telecommunication.
- Bluetooth
- Mobile phones such as GSM, CDMA, PDC, etc.
- Other High frequency circuits in general

ELECTRICAL CHARACTERISTICS:

Part Number	L(nH)	Tolerance (%)	Q Min	SRF (GHz) Min	DCR (Ω) Max	IDC (mA) Max
AISC0402-1N0☐	1.0@250MHZ	10	13@250MHZ	10.0	0.045	1360
AISC0402-2N2☐	2.2@250MHZ	10,5	18@250MHZ	6.00	0.07	960
AISC0402-2N7☐	2.7@250MHZ	10,5	15@250MHZ	6.00	0.12	640
AISC0402-3N3☐	3.3@250MHZ	10,5	20@250MHZ	6.00	0.066	840
AISC0402-3N9☐	3.9@250MHZ	10,5	20@250MHZ	6.00	0.066	840
AISC0402-4N7☐	4.7@250MHZ	10,5,2	18@250MHZ	4.50	0.2	640
AISC0402-5N6☐	5.6@250MHZ	10,5,2	20@250MHZ	4.80	0.083	760
AISC0402-6N8☐	6.8@250MHZ	10,5,2	23@250MHZ	4.80	0.26	680
AISC0402-8N2☐	8.2@250MHZ	10,5,2	25@250MHZ	4.40	0.1	680
AISC0402-10N☐	10@250MHZ	10,5,2	25@250MHZ	3.90	0.2	480
AISC0402-12N☐	12@250MHZ	10,5,2	25@250MHZ	3.60	0.12	640
AISC0402-15N☐	15@250MHZ	10,5,2	25@250MHZ	3.28	0.3	560
AISC0402-18N☐	18@250MHZ	10,5,2	25@250MHZ	3.10	0.23	420
AISC0402-22N☐	22@250MHZ	10,5,2	25@250MHZ	2.80	0.3	400
AISC0402-27N☐	27@250MHZ	10,5,2	24@250MHZ	2.48	0.52	280
AISC0402-33N☐	33@250MHZ	10,5,2	24@250MHZ	2.35	0.65	350
AISC0402-39N☐	39@250MHZ	10,5,2	25@250MHZ	2.10	0.75	200
AISC0402-47N☐	47@250MHZ	10,5,2	25@250MHZ	2.10	0.83	150
AISC0402-56N☐	56@250MHZ	10,5,2	25@250MHZ	1.76	0.97	100
AISC0402-68N☐	68@250MHZ	10,5,2	25@250MHZ	1.62	1.12	100
AISC0402-82N☐	82@250MHZ	10,5,2	25@250MHZ	1.26	1.7	50
AISC0402-R10☐	100@250MHZ	10,5,2	25@250MHZ	1.16	2	30
AISC0402-R12☐	120@250MHZ	10,5,2	25@250MHZ	1.10	2.2	30

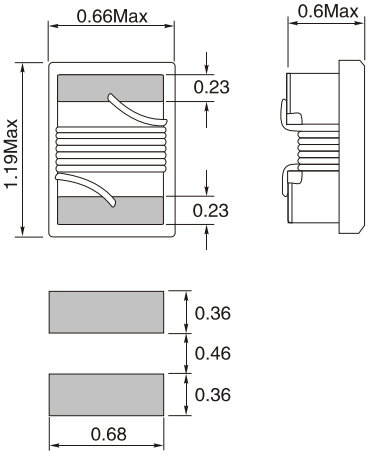
☐ G=±2%, J=±5%, K=±10%, M=±20%, N=±30%

TECHNICAL INFORMATION:

- Testing: (Equivalent acceptable)
  Inductance: HP4191A
  Q:HP4291A
  SRF:HP8753B
  RDC:measured @ 25℃
- Operating Temperature:
  Ceramic-55℃ to +125℃
- Pad metalization: Tungsten-nickel with gold flash
- Solder methods: Wave, Reflow, Vapor Phase
- Solderability: Max 260℃ for 10 seconds

PHYSICAL CHARACTERISTICS:

Dimensions:(mm)

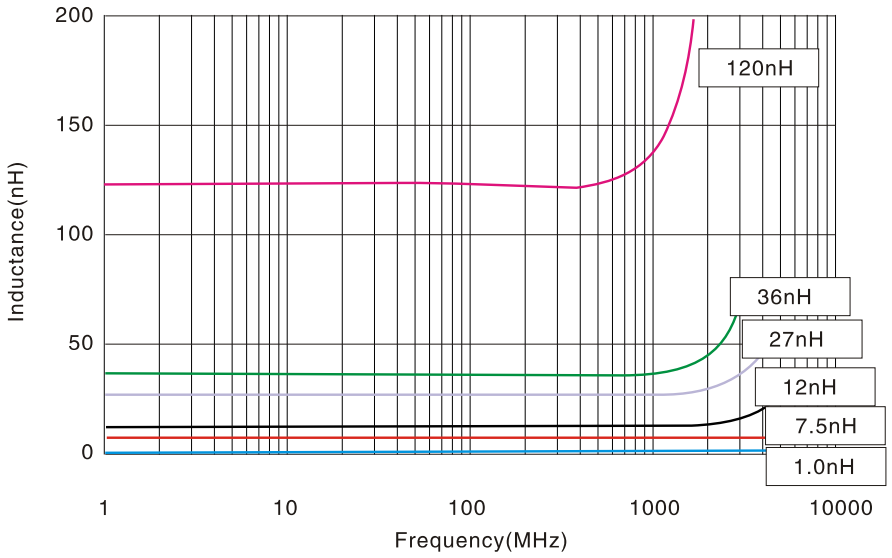


PCB LAYOUT

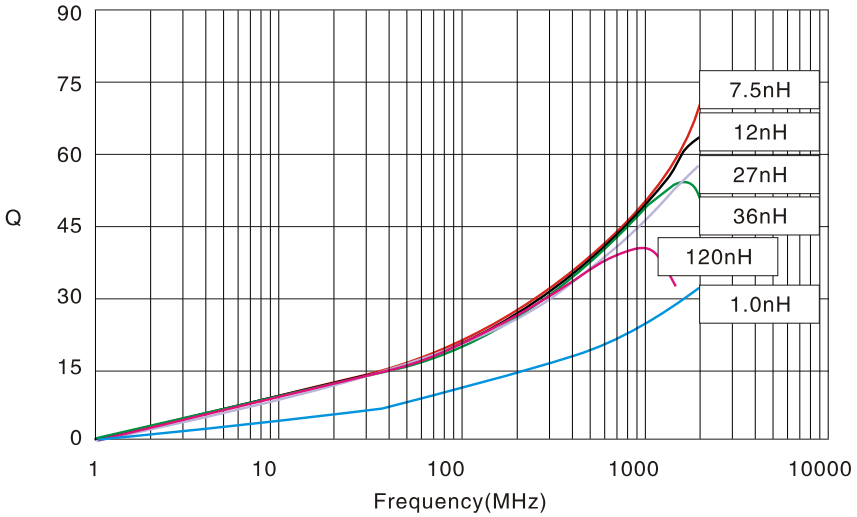
Winding

SURFACE-MOUNT WIRE WOUND CERAMIC CHIP INDUCTORS

Inductance Vs Frequency

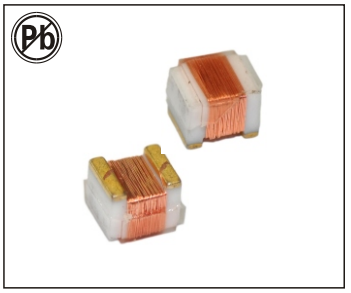


Q Vs Frequency



SURFACE-MOUNT WIRE WOUND CERAMIC CHIP INDUCTORS

AISC0603 SERIES



FEATURES:

- Multilayer monolithic construction yields high reliability
- High self-resonant frequency
- Excellentsolderability and heat resistance for either flow or reflow soldering

COMMON APPLICATIONS:

- High frequency circuits of telecommunication.
- Bluetooth
- Mobile phones such as GSM, CDMA, PDC, etc.
- Other High frequency circuits in general

ELECTRICAL CHARACTERISTICS:

Part Number	L(nH)	Tolerance (%)	Q Min	SRF (GHz) Min	DCR (Ω) Max	IDC (mA) Max
AISC0603-1N6☐	1.6@250MHZ	10	18@250MHZ	12.5	0.040	700
AISC0603-1N8☐	1.8@250MHZ	10	16@250MHZ	12.5	0.045	700
AISC0603-2N2☐	2.2@250MHZ	10	12@250MHZ	10	0.090	700
AISC0603-3N3☐	3.3@250MHZ	10	20@250MHZ	5.9	0.075	700
AISC0603-3N6☐	3.6@250MHZ	10,5	22@250MHZ	5.9	0.075	700
AISC0603-3N9☐	3.9@250MHZ	10,5	22@250MHZ	6.9	0.080	700
AISC0603-4N3☐	4.3@250MHZ	10,5	22@250MHZ	5.9	0.075	700
AISC0603-4N7☐	4.7@250MHZ	10,5	20@250MHZ	5.8	0.116	700
AISC0603-5N1☐	5.1@250MHZ	10,5	20@250MHZ	5.7	0.120	700
AISC0603-5N6☐	5.6@250MHZ	10	18@250MHZ	5.7	0.200	700
AISC0603-6N8☐	6.8@250MHZ	10,5	27@250MHZ	5.8	0.110	700
AISC0603-7N5☐	7.5@250MHZ	10,5	28@250MHZ	4.8	0.110	700
AISC0603-8N2☐	8.2@250MHZ	10	28@250MHZ	4.7	0.120	700
AISC0603-9N5☐	9.5@250MHZ	10	26@250MHZ	5.4	0.150	700
AISC0603-10N☐	10@250MHZ	10	31@250MHZ	4.8	0.130	700
AISC0603-12N☐	12@250MHZ	10	35@250MHZ	4	0.130	700
AISC0603-15N☐	15@250MHZ	10	30@250MHZ	4	0.150	700
AISC0603-18N☐	18@250MHZ	10	35@250MHZ	3.1	0.170	700
AISC0603-22N☐	22@250MHZ	10	38@250MHZ	3	0.190	700
AISC0603-27N☐	27@250MHZ	10	36@250MHZ	2.8	0.220	600
AISC0603-33N☐	33@250MHZ	10	36@250MHZ	2.3	0.220	600
AISC0603-36N☐	36@250MHZ	10	36@250MHZ	2.08	0.250	600
AISC0603-39N☐	39@250MHZ	10	40@250MHZ	2.2	0.250	600
AISC0603-43N☐	43@250MHZ	10	36@250MHZ	2	0.280	600
AISC0603-47N☐	47@200MHz	10	36@200MHz	2	0.280	600
AISC0603-56N☐	56@200MHz	10	38@200MHz	1.9	0.280	600
AISC0603-68N☐	68@200MHz	10	36@200MHz	1.7	0.340	600
AISC0603-75N☐	75@150MHz	10	30@150MHz	1.4	0.600	400
AISC0603-82N☐	82@150MHz	10	34@150MHz	1.7	0.550	400
AISC0603-R10☐	100@150MHz	10	30@150MHz	1.4	0.630	400
AISC0603-R12☐	120@150MHz	10	32@150MHz	1.3	0.730	300
AISC0603-R15☐	150@150MHz	10	28@150MHz	0.99	0.800	280
AISC0603-R18☐	180@100MHz	10	25@100MHz	0.99	1.450	240
AISC0603-R20☐	200@100MHz	10	25@100MHz	0.9	1.550	200
AISC0603-R22☐	220@100MHz	10	25@100MHz	0.9	2.100	200
AISC0603-R27☐	270@100MHz	10	24@100MHz	0.9	2.300	170
AISC0603-R33☐	330@100MHz	10	25@100MHz	0.9	3.890	100
AISC0603-R39☐	390@100MHz	10	25@100MHz	0.8	4.350	100

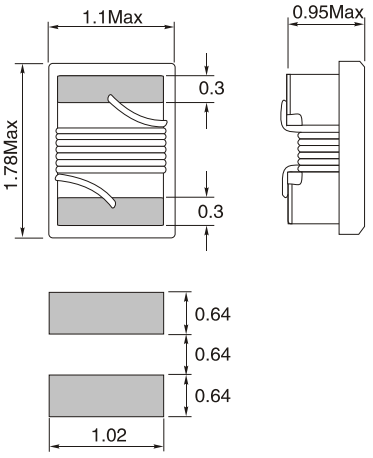
☐ G=±2%, J=±5%, K=±10%, M=±20%, N=±30%

TECHNICAL INFORMATION:

- Testing: (Equivalent acceptable)
  Inductance: HP4191A
  Q:HP4291A
  SRF:HP8753B
  RDC:measured @ 25℃
- Operating Temperature:
  Ceramic-55℃ to +125℃
- Pad metalization: Tungsten-nickel with gold flash
- Solder methods: Wave, Reflow, Vapor Phase
- Solderability: Max 260℃ for 10 seconds

PHYSICAL CHARACTERISTICS:

Dimensions:(mm)

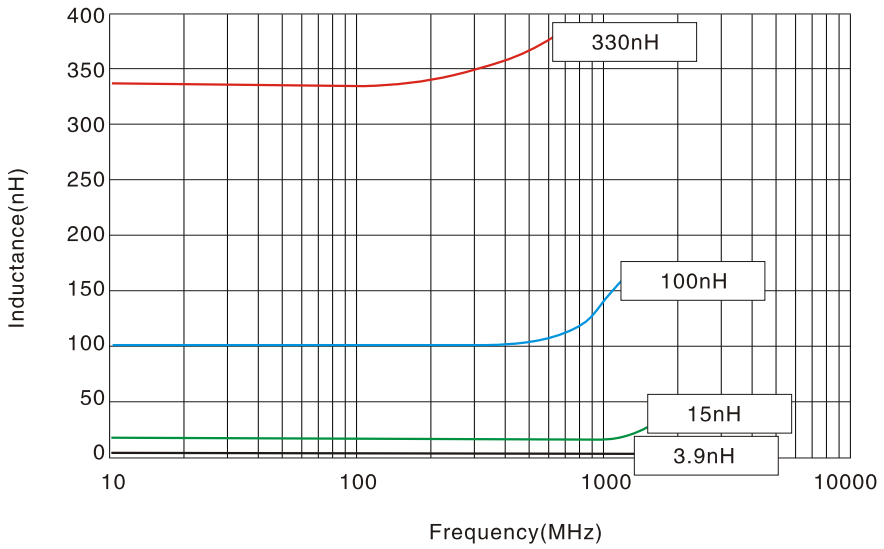


PCB LAYOUT

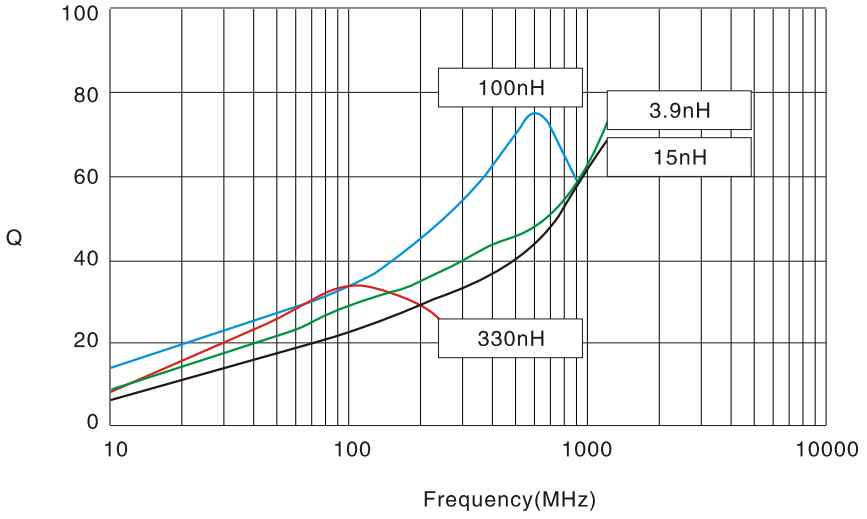
Winding

SURFACE-MOUNT WIRE WOUND CERAMIC CHIP INDUCTORS

Inductance vs Frequency

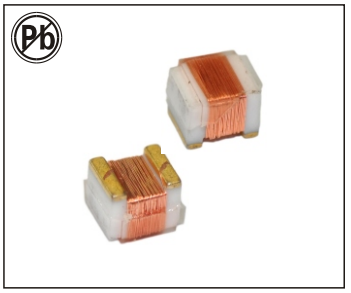


Q vs Frequency



SURFACE-MOUNT WIRE WOUND CERAMIC CHIP INDUCTORS

AISC0805 SERIES



FEATURES:

- Multilayer monolithic construction yields high reliability
- High self-resonant frequency
- Excellentsolderability and heat resistance for either flow or reflow soldering

COMMON APPLICATIONS:

- High frequency circuits of telecommunication.
- Bluetooth
- Mobile phones such as GSM, CDMA, PDC, etc.
- Other High frequency circuits in general

ELECTRICAL CHARACTERISTICS:

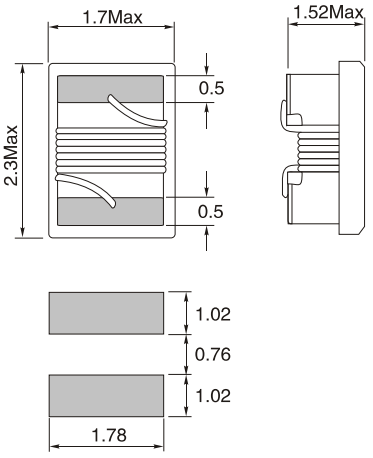
Part Number	L(nH)	Tolerance (%)	Q Min	SRF (GHz) Min	DCR (Ω) Max	IDC (mA) Max
AISC0805-2N2☐	2.2@250MHz	10	50@1500MHz	8.50	0.030	800
AISC0805-2N7☐	2.7@250MHz	10,5	50@1500MHz	8.00	0.045	800
AISC0805-3N3☐	3.3@250MHz	10	35@1500MHz	7.90	0.090	600
AISC0805-4N7☐	4.7@250MHz	10	40@1000MHz	6.00	0.050	600
AISC0805-5N6☐	5.6@250MHz	10,5	50@1000MHz	5.50	0.065	600
AISC0805-6N8☐	6.8@250MHz	10,5	50@1000MHz	5.50	0.110	600
AISC0805-8N2☐	8.2@250MHz	10,5	35@1000MHz	4.70	0.200	600
AISC0805-10N☐	10@250MHz	10,5,2	50@500MHz	4.20	0.150	600
AISC0805-12N☐	12@250MHz	10,5,2	50@500MHz	4.00	0.150	600
AISC0805-15N☐	15@250MHz	10,5,2	45@500MHz	3.40	0.170	600
AISC0805-18N☐	18@250MHz	10,5,2	55@500MHz	3.30	0.200	600
AISC0805-22N☐	22@250MHz	10,5,2	55@500MHz	2.60	0.220	500
AISC0805-27N☐	27@250MHz	10,5,2	55@500MHz	2.50	0.250	500
AISC0805-33N☐	33@250MHz	10,5,2	55@500MHz	2.05	0.270	500
AISC0805-39N☐	39@250MHz	10,5,2	55@500MHz	2.00	0.290	500
AISC0805-47N☐	47@200MHz	10,5,2	55@500MHz	1.65	0.310	500
AISC0805-56N☐	56@200MHz	10,5,2	55@500MHz	1.55	0.340	500
AISC0805-68N☐	68@200MHz	10,5,2	55@500MHz	1.45	0.380	500
AISC0805-75N☐	75@200MHz	10,5,2	55@500MHz	1.40	0.400	400
AISC0805-82N☐	82@150MHz	10,5,2	55@500MHz	1.30	0.420	400
AISC0805-R10☐	100@150MHz	10,5,2	50@500MHz	1.20	0.460	400
AISC0805-R12☐	120@150MHz	10,5,2	45@250MHz	1.10	0.510	400
AISC0805-R15☐	150@100MHz	10,5,2	45@250MHz	0.92	0.560	400
AISC0805-R18☐	180@100MHz	10,5,2	45@250MHz	0.87	0.640	400
AISC0805-R22☐	220@100MHz	10,5,2	40@250MHz	0.85	1.050	400
AISC0805-R27☐	270@100MHz	10,5,2	40@250MHz	0.65	1.100	350
AISC0805-R33☐	330@100MHz	10,5	40@250MHz	0.60	1.400	310
AISC0805-R39☐	390@100MHz	10,5	40@250MHz	0.56	1.500	290
AISC0805-R47☐	470@50MHz	10,5	33@100MHz	0.38	2.000	250
AISC0805-R56☐	560@25MHz	10,5	23@50MHz	0.34	1.900	230
AISC0805-R68☐	680@25MHz	10,5	23@50MHz	0.30	2.100	190
AISC0805-R75☐	750@25MHz	10,5	23@50MHz	0.28	2.120	180
AISC0805-R82☐	820@25MHz	10,5	23@50MHz	0.25	2.140	180
AISC0805-R91☐	910@25MHz	10,5	20@50MHz	0.22	2.280	180
AISC0805-1R0☐	1000@25MHz	10,5	20@50MHz	0.20	2.400	170
AISC0805-1R2☐	1200@7.9MHz	10,5	18@50MHz	0.18	2.550	170
AISC0805-1R5☐	1500@7.9MHz	10,5	18@50MHz	0.17	2.800	160
AISC0805-1R8☐	1800@7.9MHz	10,5	18@50MHz	0.14	3.800	150
AISC0805-2R2☐	2200@7.9MHz	10,5	16@7.9MHz	0.05	4.200	150

TECHNICAL INFORMATION:

- Testing: (Equivalent acceptable)
  Inductance: HP4191A
  Q:HP4291A
  SRF:HP8753B
  RDC:measured @ 25℃
- Operating Temperature:
  Ceramic-55℃ to +125℃
- Pad metalization: Tungsten-nickel with gold flash
- Solder methods: Wave, Reflow, Vapor Phase
- Solderability: Max 260℃ for 10 seconds

PHYSICAL CHARACTERISTICS:

Dimensions:(mm)



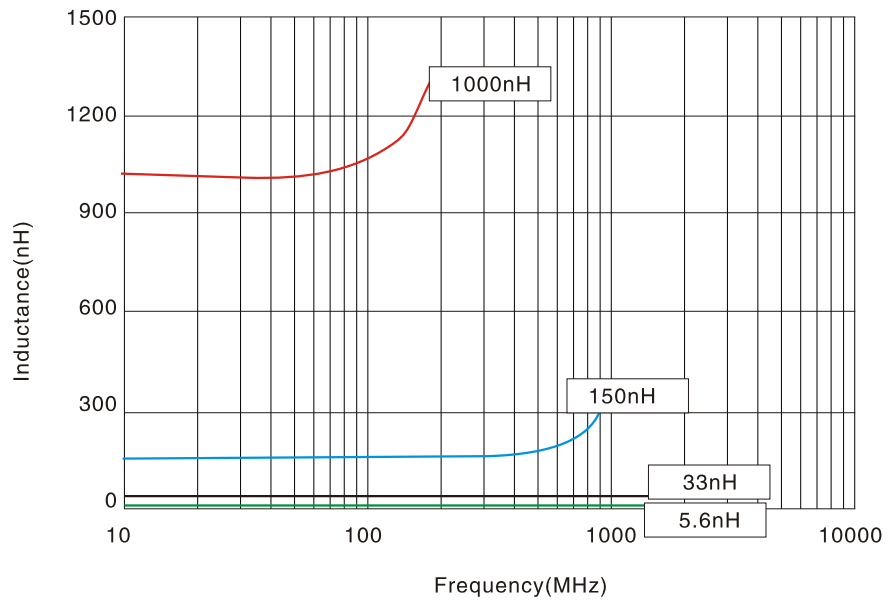
PCB LAYOUT

Winding

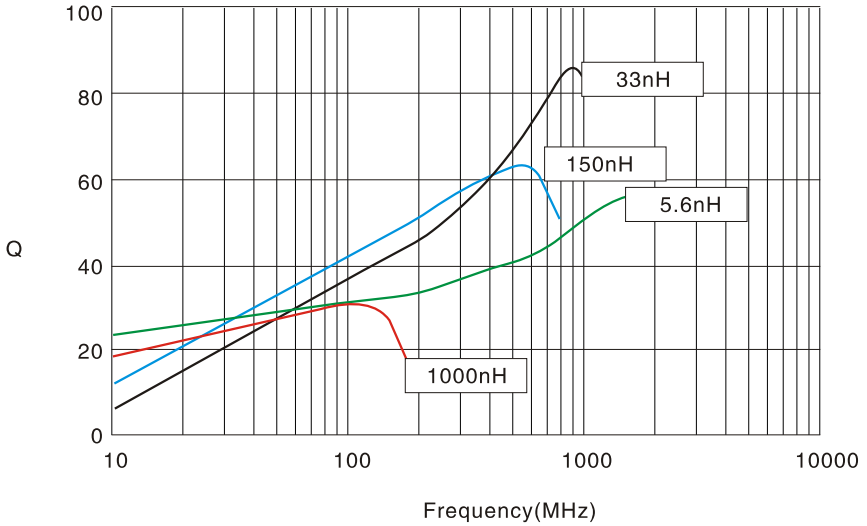
☐ G=±2%, J=±5%, K=±10%,
M=±20%, N=±30%

SURFACE-MOUNT WIRE WOUND CERAMIC CHIP INDUCTORS

Inductance vs Frequency

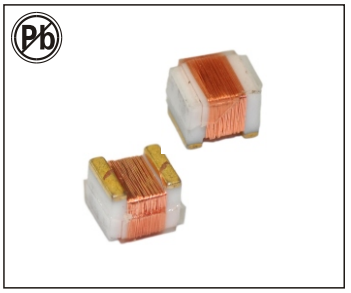


Q vs Frequency



SURFACE-MOUNT WIRE WOUND CERAMIC CHIP INDUCTORS

AISC1008 SERIES



FEATURES:

- Multilayer monolithic construction yields high reliability
- High self-resonant frequency
- Excellentsolderability and heat resistance for either flow or reflow soldering

COMMON APPLICATIONS:

- High frequency circuits of telecommunication.
- Bluetooth
- Mobile phones such as GSM, CDMA, PDC, etc.
- Other High frequency circuits in general

ELECTRICAL CHARACTERISTICS:

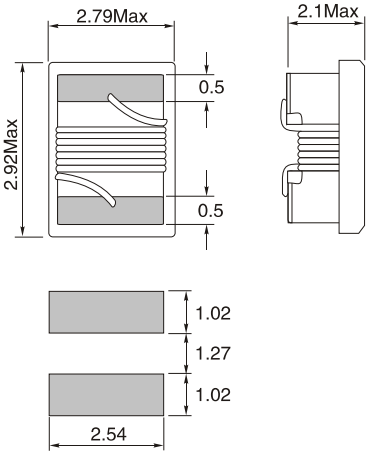
Part Number	L(nH)	Tolerance (%)	Q Min	SRF (GHz) Min	DCR (Ω) Max	IDC (mA) Max
AISC1008-3N9□	3.9@50MHz	10,5	50@1500MHz	6.00	0.035	1000
AISC1008-4N7□	4.7@50MHz	10,5	50@1500MHz	6.00	0.045	1000
AISC1008-5N6□	5.6@50MHz	10,5	30@1000MHz	6.00	0.180	1000
AISC1008-8N2□	8.2 @50MHz	10,5	50@1000MHz	5.00	0.050	1000
AISC1008-10N□	10@50MHz	10,5,2	50@500MHz	4.10	0.080	1000
AISC1008-12N□	12@50MHz	10,5,2	50@500MHz	3.30	0.090	1000
AISC1008-15N□	15@50MHz	10,5,2	45@500MHz	2.50	0.150	1000
AISC1008-18N□	18@50MHz	10,5,2	50@350MHz	2.50	0.110	1000
AISC1008-22N□	22@50MHz	10,5,2	55@350MHz	2.40	0.120	1000
AISC1008-27N□	27@50MHz	10,5,2	55@350MHz	1.60	0.130	1000
AISC1008-33N□	33@50MHz	10,5,2	60@350MHz	1.60	0.140	1000
AISC1008-39N□	39@50MHz	10,5,2	60@350MHz	1.50	0.150	1000
AISC1008-47N□	47@50MHz	10,5,2	65@350MHz	1.50	0.160	1000
AISC1008-56N□	56@50MHz	10,5,2	65@350MHz	1.10	0.180	1000
AISC1008-68N□	68@50MHz	10,5,2	65@350MHz	1.00	0.200	1000
AISC1008-82N□	82@50MHz	10,5,2	60@350MHz	1.00	0.220	1000
AISC1008-R10□	100@25MHz	10,5,2	60@350MHz	1.00	0.560	650
AISC1008-R12□	120@25MHz	10,5,2	60@350MHz	0.95	0.630	650
AISC1008-R15□	150@25MHz	10,5	45@100MHz	0.80	0.700	580
AISC1008-R18□	180@25MHz	10,5	45@100MHz	0.64	0.770	620
AISC1008-R22□	220@25MHz	10,5	45@100MHz	0.62	0.840	500
AISC1008-R27□	270@25MHz	10,5	45@100MHz	0.60	0.910	500
AISC1008-R33□	330@25MHz	10,5	45@100MHz	0.50	1.050	450
AISC1008-R39□	390@25MHz	10,5	45@100MHz	0.48	1.120	470
AISC1008-R47□	470@25MHz	10,5	45@100MHz	0.45	1.190	470
AISC1008-R56□	560@25MHz	10,5	45@100MHz	0.415	1.330	400
AISC1008-R68□	680@25MHz	10,5	45@100MHz	0.375	1.470	400
AISC1008-R82□	820@25MHz	10,5	45@100MHz	0.25	1.610	400
AISC1008-1R0□	1000@25MHz	10,5	35@50MHz	0.21	1.750	370
AISC1008-1R2□	1200@7.9MHz	10,5	35@50MHz	0.20	2.000	310
AISC1008-1R5□	1500@7.9MHz	10,5	28@50MHz	0.18	2.300	330
AISC1008-1R8□	1800@7.9MHz	10,5	28@50MHz	0.16	2.600	300
AISC1008-2R2□	2200@7.9MHz	10,5	20@50MHz	0.09	2.800	280
AISC1008-2R7□	2700@7.9MHz	10,5	22@25MHz	0.08	3.200	290
AISC1008-3R3□	3300@7.9MHz	10,5	22@25MHz	0.07	3.400	290
AISC1008-3R9□	3900@7.9MHz	10,5	16@25MHz	0.06	3.600	260
AISC1008-4R7□	4700@7.9MHz	10,5	18@25MHz	0.06	4.000	260
AISC1008-5R6□	5600@7.9MHz	10,5	18@7.9MHz	0.06	7.600	240
AISC1008-6R8□	6800@7.9MHz	10,5	18@7.9MHz	0.05	8.200	200
AISC1008-8R2□	8200@7.9MHz	10,5	18@7.9MHz	0.04	8.200	170
AISC1008-100□	10000@7.9MHz	10,5	20@7.9MHz	0.04	9.100	160

TECHNICAL INFORMATION:

- Testing: (Equivalent acceptable)
  Inductance: HP4191A
  Q:HP4291A
  SRF:HP8753B
  RDC:measured @ 25℃
- Operating Temperature:
  Ceramic-55℃ to +125℃
- Pad metalization: Tungsten-nickel with gold flash
- Solder methods: Wave, Reflow, Vapor Phase
- Solderability: Max 260℃ for 10 seconds

PHYSICAL CHARACTERISTICS:

Dimensions:(mm)



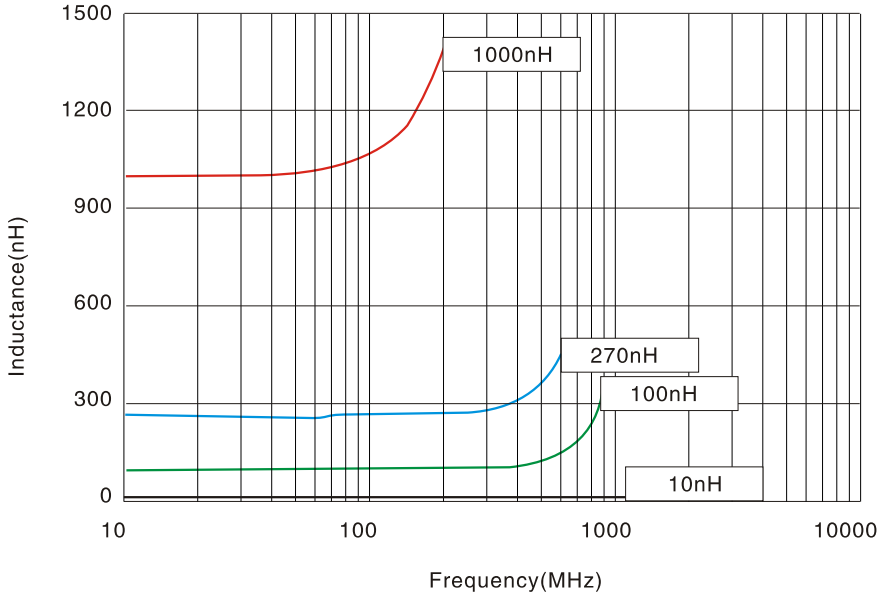
PCB LAYOUT

Winding

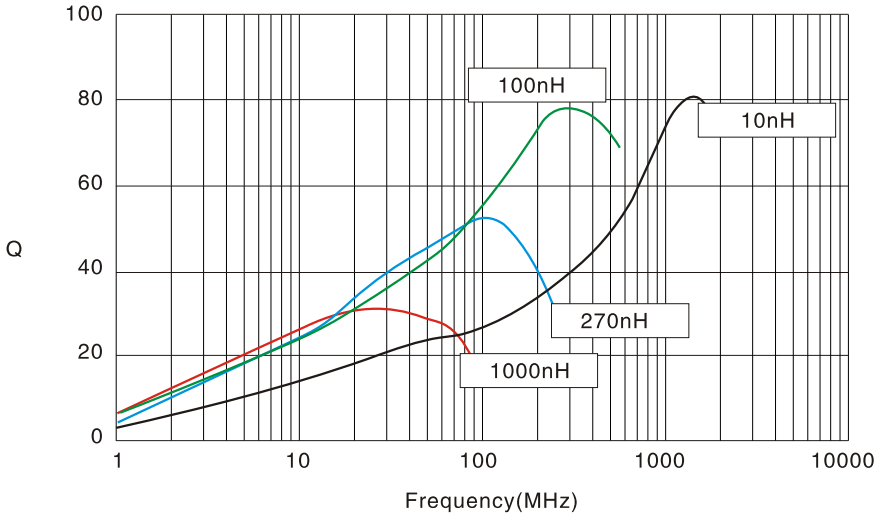
□ G=±2%, J=±5%, K=±10%,
M=±20%, N=±30%

SURFACE-MOUNT WIRE WOUND CERAMIC CHIP INDUCTORS

Inductance vs Frequency

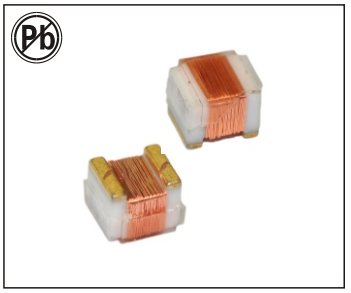


Q vs Frequency



SURFACE-MOUNT WIRE WOUND CERAMIC CHIP INDUCTORS

AISC1210 SERIES



FEATURES:

- Multilayer monolithic construction yields high reliability
- High self-resonant frequency
- Excellentsolderability and heat resistance for either flow or reflow soldering

COMMON APPLICATIONS:

- High frequency circuits of telecommunication.
- Bluetooth
- Mobile phones such as GSM, CDMA, PDC, etc.
- Other High frequency circuits in general

ELECTRICAL CHARACTERISTICS:

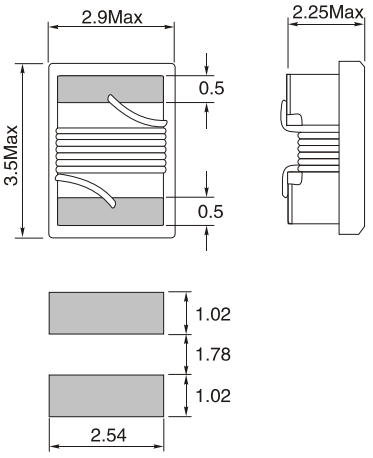
Part Number	L(nH)	Tolerance (%)	Q Min	SRF (GHz) Min	DCR (Ω) Max	IDC (mA) Max
AISC1210-3N9□	3.9@100MHz	10	30@300MHz	6.00	0.050	1000
AISC1210-4N7□	4.7@100MHz	10,5	30@300MHz	5.80	0.065	1000
AISC1210-8N2□	8.2@100MHz	10	30@300MHz	5.50	0.070	1000
AISC1210-10N□	10@100MHz	10,5,2	40@300MHz	4.00	0.080	1000
AISC1210-12N□	12@100MHz	10,5	40@300MHz	3.20	0.080	1000
AISC1210-15N□	15@100MHz	10,5	40@300MHz	3.20	0.100	1000
AISC1210-18N□	18@100MHz	10,5,2	50@300MHz	2.80	0.100	1000
AISC1210-22N□	22@100MHz	10,5	50@300MHz	2.00	0.100	1000
AISC1210-27N□	27@100MHz	10,5,2	50@300MHz	1.80	0.110	1000
AISC1210-33N□	33@100MHz	10,5,2	55@300MHz	1.80	0.110	1000
AISC1210-39N□	39@100MHz	10,5,2	55@300MHz	1.80	0.120	1000
AISC1210-47N□	47@100MHz	10,5,2	55@300MHz	1.50	0.130	1000
AISC1210-56N□	56@100MHz	10,5,2	55@300MHz	1.45	0.140	1000
AISC1210-68N□	68@100MHz	10,5,2	55@300MHz	1.20	0.150	900
AISC1210-82N□	82@100MHz	10,5,2	55@300MHz	1.00	0.200	900
AISC1210-R10□	100@100MHz	10,5,2	55@300MHz	0.90	0.210	850
AISC1210-R12□	120@100MHz	10,5,2	60@300MHz	0.80	0.210	800
AISC1210-R15□	150@100MHz	10,5,2	60@300MHz	0.78	0.250	750
AISC1210-R18□	180@50MHz	10,5,2	60@300MHz	0.76	0.300	700
AISC1210-R22□	220@50MHz	10,5,2	60@300MHz	0.65	0.320	670
AISC1210-R27□	270@50MHz	10,5,2	55@300MHz	0.62	0.340	630
AISC1210-R33□	330@50MHz	10,5,2	45@150MHz	0.60	0.380	590
AISC1210-R39□	390@50MHz	10,5,2	45@150MHz	0.51	0.580	530
AISC1210-R47□	470@50MHz	10,5,2	45@150MHz	0.50	0.800	490
AISC1210-R56□	560@35MHz	10,5	45@150MHz	0.42	1.100	460
AISC1210-R68□	680@35MHz	10,5,2	45@150MHz	0.40	1.200	430
AISC1210-R75□	750@35MHz	10,5,2	45@150MHz	0.38	1.70	400
AISC1210-R82□	820@35MHz	10,5,2	45@150MHz	0.37	1.820	400
AISC1210-1R0□	1000@35MHz	10,5,2	45@150MHz	0.34	1.850	320
AISC1210-1R2□	1200@35MHz	10,5	35@150MHz	0.22	1.870	300
AISC1210-1R5□	1500@7.9MHz	10,5	30@50MHz	0.16	1.950	310
AISC1210-1R8□	1800@7.9MHz	10,5	30@50MHz	0.16	2.250	310
AISC1210-2R2□	2200@7.9MHz	10,5	30@50MHz	0.11	2.410	310
AISC1210-2R7□	2700@7.9MHz	10,5	25@25MHz	0.10	2.850	300
AISC1210-3R3□	3300@7.9MHz	10,5	20@25MHz	0.09	3.120	300
AISC1210-3R9□	3900@7.9MHz	10,5	20@25MHz	0.08	3.600	290
AISC1210-4R7□	4700@7.9MHz	10,5	16@25MHz	0.06	4.000	280
AISC1210-5R6□	5600@7.9MHz	10,5	20@7.9MHz	0.06	5.000	250
AISC1210-6R8□	6800@7.9MHz	10,5	20@7.9MHz	0.06	8.000	230
AISC1210-8R2□	8200@7.9MHz	10,5	20@7.9MHz	0.05	8.600	170
AISC1210-100□	10000@7.9MHz	10,5	22@7.9MHz	0.02	6.800	200

TECHNICAL INFORMATION:

- Testing: (Equivalent acceptable)
  Inductance: HP4191A
  Q:HP4291A
  SRF:HP8753B
  RDC:measured @ 25℃
- Operating Temperature:
  Ceramic-55℃ to +125℃
- Pad metalization: Tungsten-nickel with gold flash
- Solder methods: Wave, Reflow, Vapor Phase
- Solderability: Max 260℃ for 10 seconds

PHYSICAL CHARACTERISTICS:

Dimensions:(mm)



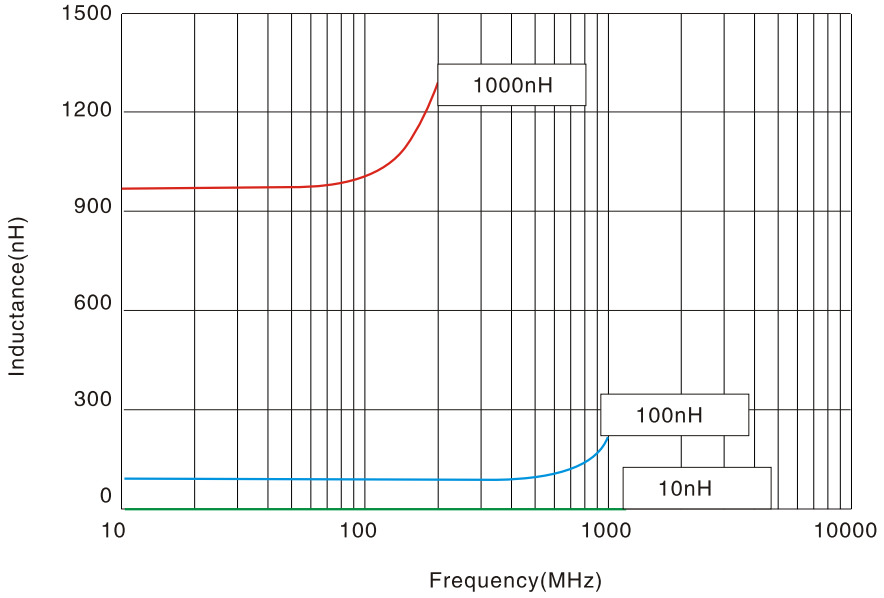
PCB LAYOUT

Winding

□ G=±2%, J=±5%, K=±10%,
M=±20%, N=±30%

SURFACE-MOUNT WIRE WOUND CERAMIC CHIP INDUCTORS

Inductance vs Frequency



Q vs Frequency